

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	[WAFER STRUCTURE AND BUMPING PROCESS THEREOF]
Application Type :	regular, utility
Attorney Docket Number :	11579-US-PA
Correspondence address:	
Customer Number:	31561
	
Priority Data:	
Doc.No: 92118830; Country -TW ; Date: 2003-07-10 us-priority-claimed	
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